Diode Modules MDx300

$I_{F(AV)}$	300A
V_{RRM}	1900~2500V
I_{FSM}	10 A×10^3
I^2t	500A^2 S*10^3

Features：

- Isolated mounting base 3000V~
- Pressure contact technology with Incrtased power cycling capability
- Space and weight savings

Typical Applications

- AC/DC Motor drives
- Various rectifiers
- DC supply for PWM inverter

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T_j(°C)	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled,T_C=100°C	150			300	A
$I_{F\ (RMS)}$	RMS forward current		150			471	A
V_{RRM}	Repetitive peak reverse voltage	V_{RRM} tp=10ms V_{RsM}= V_{RRM}+100V	150	1900		2500	V
I_{RRM}	Repetitive peak current	at V_{RRM}	150			20	mA
I_{FSM}	Surge forward current	10ms half sine wave V_R=0.6V_{RRM}	150			10	KA
I^2t	I^2T for fusing coordination					500	A^2s*10^3
V_{FO}	Threshold voltage		150			0.80	V
r_F	Forward slop resistance					0.50	mΩ
V_{FM}	Peak forward voltage	I_{FM}=900A	25			1.45	V
$R_{th(j-c)}$	Thermal resistance Junction to case	At 180^0 sine, Single side cooled				0.120	°C /W
$R_{th(c-h)}$	Thermal resistance case to heatsink	At 180^0 sine, Single side cooled				0.04	°C /W
V_{iso}	Isolation voltage	50Hz,R.M.S,t=1min,I_{iso}:1mA(max)		3000			V
F_m	Terminal connection torque(M8)				12		N·m
	Mounting torque(M6)				6		N·m
T_{stg}	Stored temperature			-40		125	°C
W_t	Weight				860		g
Outline							

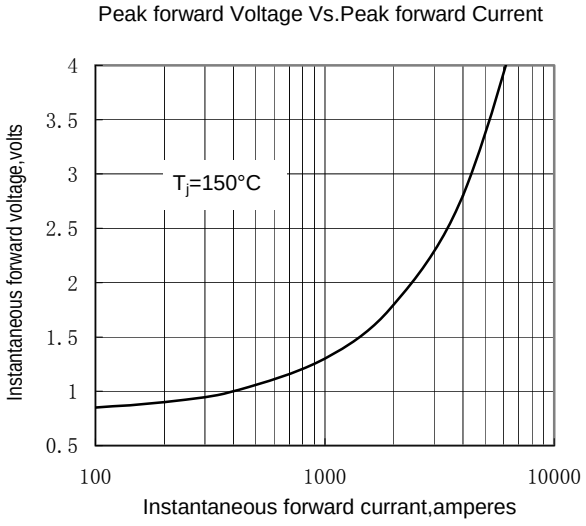

Fig.1

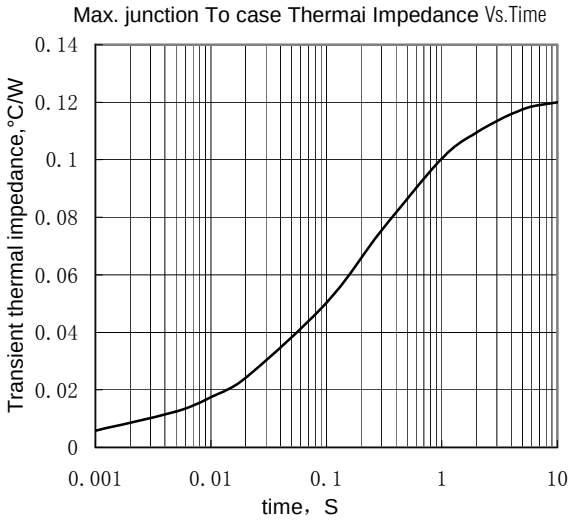

Fig.2

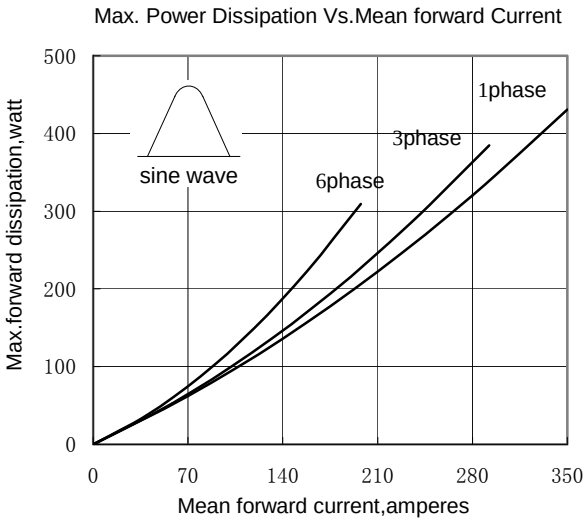

Fig.3

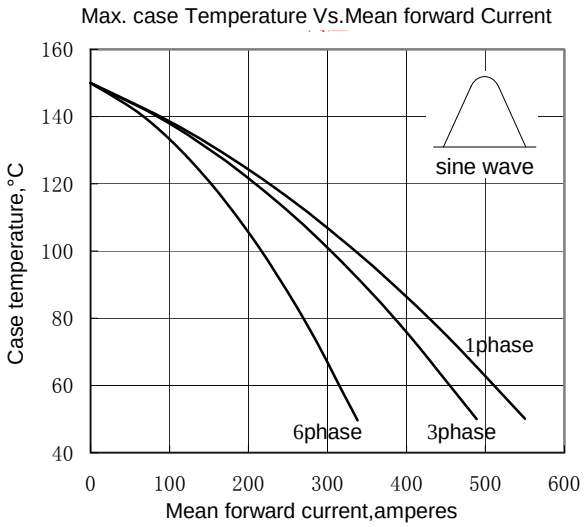

Fig.4

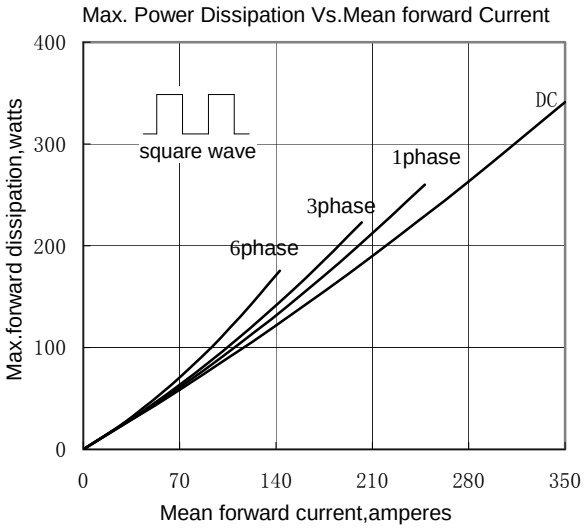

Fig.5

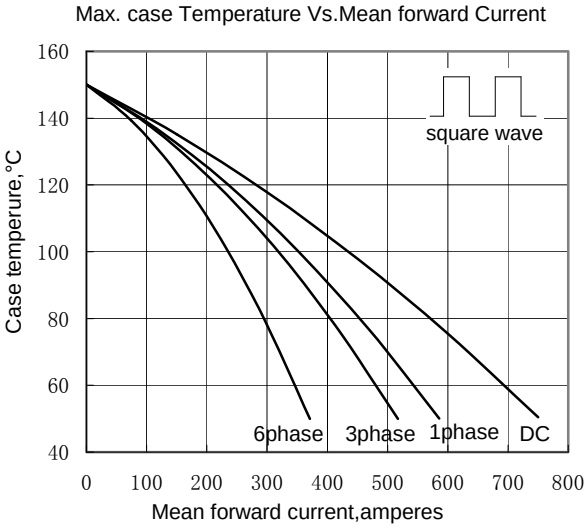

Fig.6

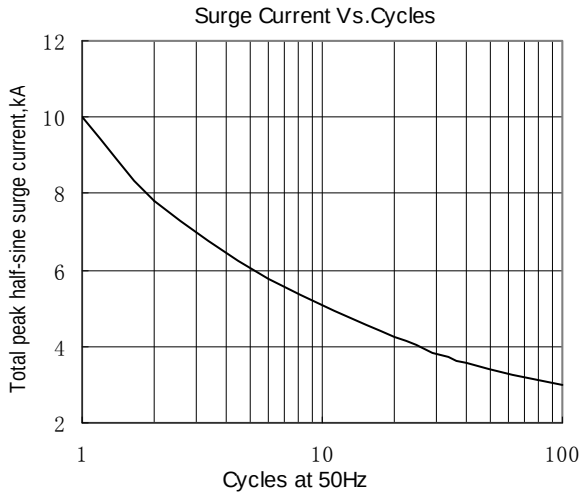

Fig.7

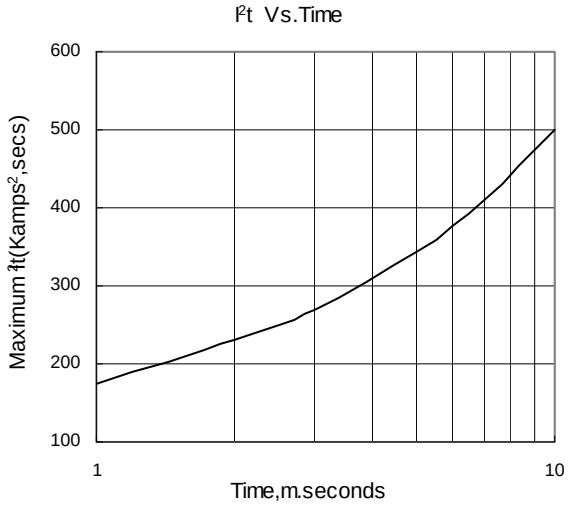

Fig.8

Outline: